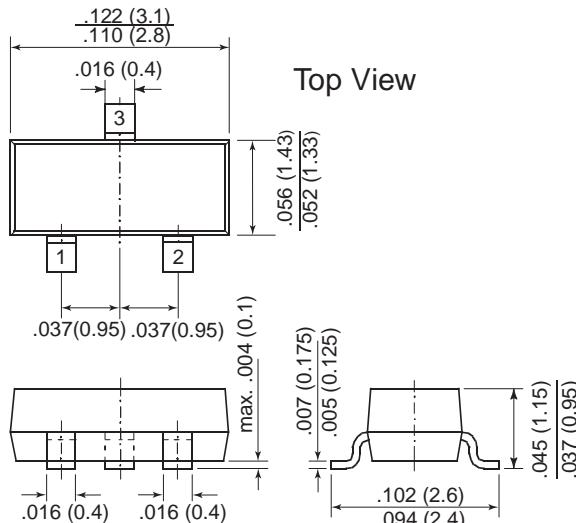
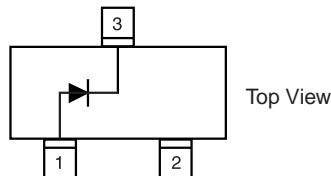
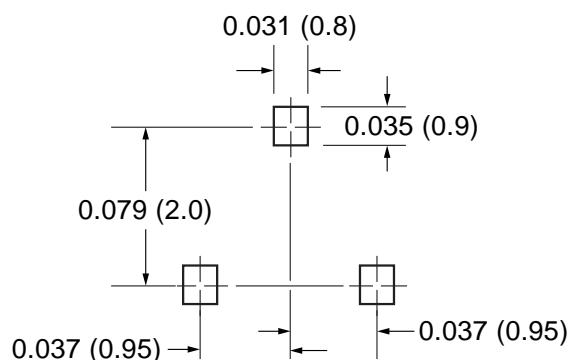



**TO-236AB (SOT-23)**


### Marking A2



### Mounting Pad Layout



### Features

- Silicon Epitaxial Planar Diodes
- Fast switching diode in case SOT-23, especially suited for automatic insertion.
- This diodes are also available in other case styles including: the DO-35 case with the type designation 1N4448, the Mini-MELF case with the type designation LL4448, and the SOD-123 case with the type designation 1N4448W.

### Mechanical Data

**Case:** SOT-23 Plastic Package

**Weight:** approx. 0.008g

**Packaging Codes/Options:**

E8/10K per 13" reel (8mm tape), 30K/box  
E9/3K per 7" reel (8mm tape), 30K/box

### Maximum Ratings and Thermal Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Reverse Voltage	$V_R$	75	V
Peak Reverse Voltage	$V_{RM}$	100	V
Rectified Current (Average) Half Wave Rectification with Resist. Load at $T_{amb} = 25^\circ\text{C}$ and $\geq f \geq 50\text{Hz}$	$I_{F(AV)}$	150 <sup>(1)</sup>	mA
Surge Forward Current at $t < 1\text{s}$ and $T_j = 25^\circ\text{C}$	$I_{FSM}$	500	mA
Power Dissipation up to $T_{amb} = 25^\circ\text{C}$	$P_{tot}$	350 <sup>(1)</sup>	mW
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	450 <sup>(1)</sup>	°C/W
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_s$	-65 to +150	°C

**Note:**

(1) Device on fiberglass substrate, see layout on next page.

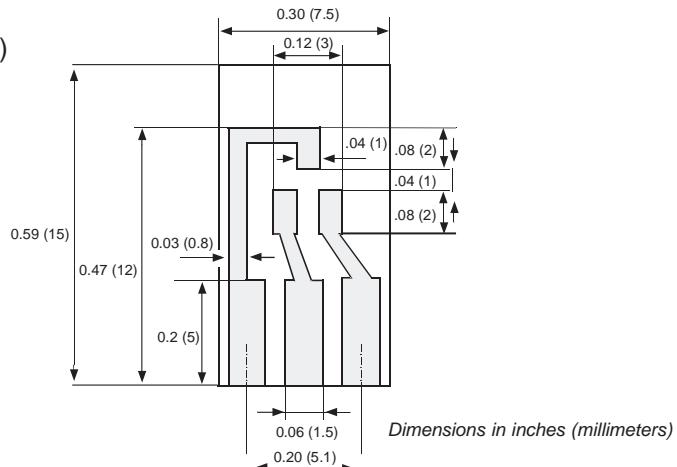
## Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 5mA I <sub>F</sub> = 100mA	0.62	—	0.72	V
Leakage Current	I <sub>R</sub>	V <sub>R</sub> = 70V V <sub>R</sub> = 70V, T <sub>j</sub> = 150°C V <sub>R</sub> = 25V, T <sub>j</sub> = 150°C	—	—	2.5 50 30	μA μA μA
Capacitance	C <sub>tot</sub>	V <sub>F</sub> = V <sub>R</sub> = 0, f = 1MHz	—	—	4	pF
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 10mA, I <sub>R</sub> = 10mA V <sub>R</sub> = 6V, R <sub>L</sub> = 100Ω	—	—	4	ns

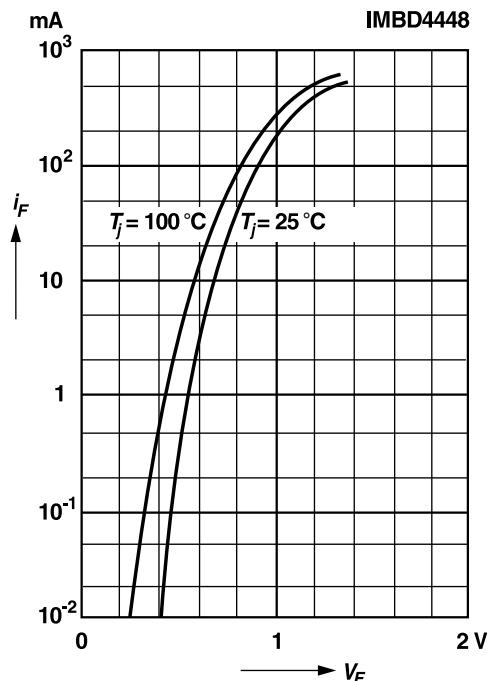
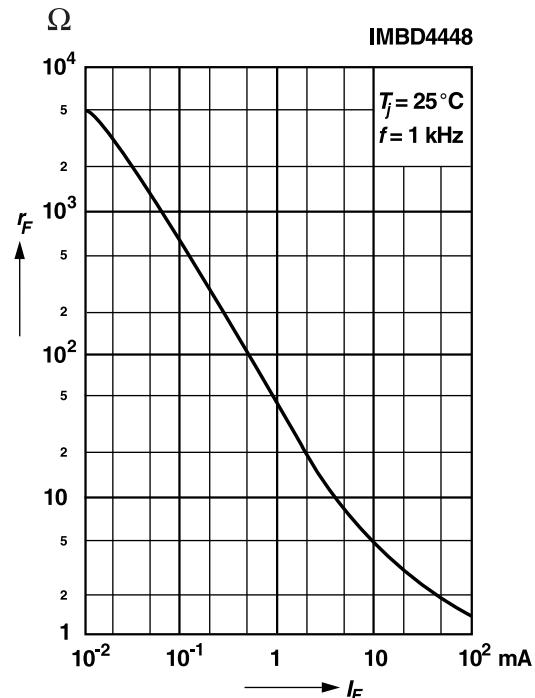
(1)Device on fiberglass substrate, see layout (SOT-23).

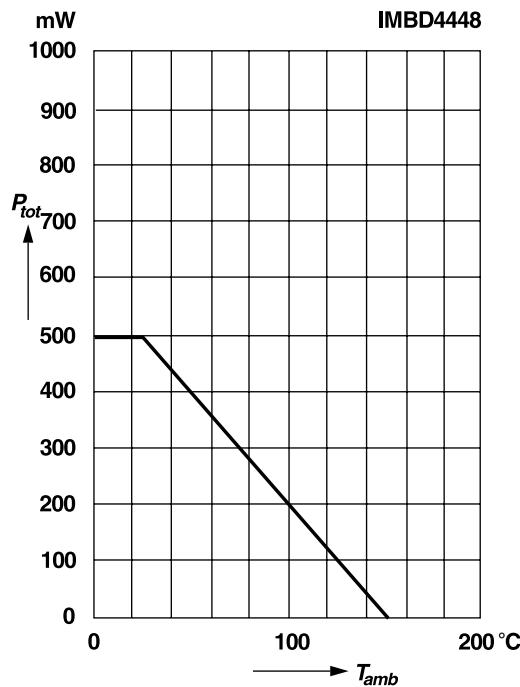
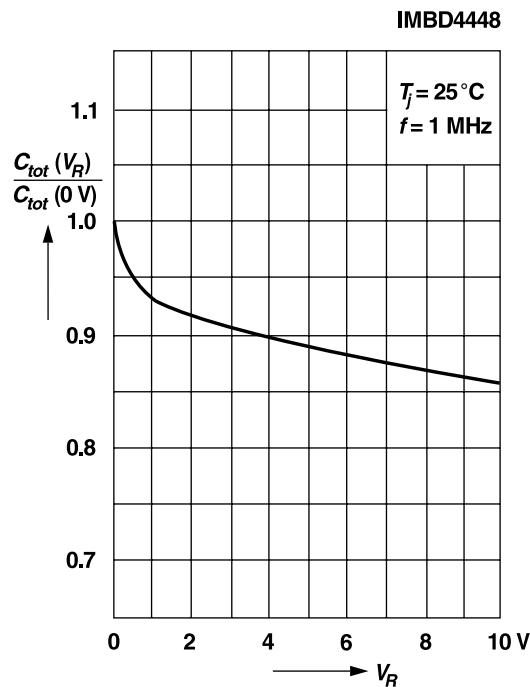
## Layout for R<sub>thJA</sub> test

Thickness: Fiberglass 0.059 in. (1.5 mm)  
Copper leads 0.012 in. (0.3 mm)



**Ratings and  
Characteristic Curves** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

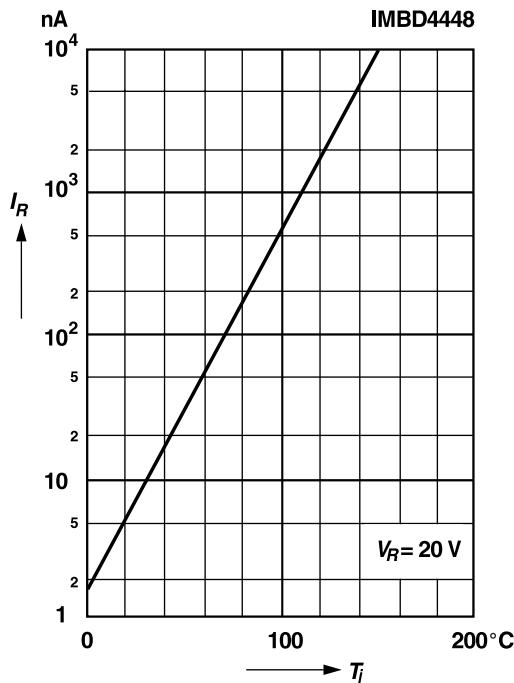
**Forward characteristics**

**Dynamic forward resistance  
versus forward current**

**Admissible power dissipation  
versus ambient temperature**

 For conditions, see footnote in table  
 "Absolute Maximum Ratings"

**Relative capacitance  
versus reverse voltage**


## Ratings and Characteristic Curves

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

### Leakage current versus junction temperature



### Admissible repetitive peak forward current versus pulse duration

For conditions, see footnote in table "Absolute Maximum Ratings"

